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FEB 03 2003

TECHNOLOGY CENTER 2800

**U.S. PATENT AND TRADEMARK OFFICE  
FACSIMILE TRANSMISSION COVER SHEET**

February 3, 2003

<b>To:</b> In re the Application of  Shunichi SEKI et al.  Application No.: 09/423,969 November 17, 1999  <b>For:</b> METHOD OF FORMING THIN FILM PATTERNING SUBSTRATE INCLUDING FORMATION OF BANKS (AS AMENDED)	<b>FOR FILING IN THE U.S. PATENT AND TRADEMARK OFFICE</b>  Group Art Unit: 2814  Docket No.: 104741
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**Examiner:** A. Mai **Facsimile:** (703) 308-7722**From:** James A. Oliff/Michael Britton**Prepared By:** Jfl **Number of Pages Sent (Including cover sheet):** 16**Comments:**

Attached is our proposed response to the Office Action mailed September 13, 2003, for the above-identified application.

The following papers are attached:

- a. Proposed Amendment After Final (8 pages)
- b. Proposed Appendix (6 pages)

**Sent by:** \_\_\_\_\_

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**PROPOSED****PATENT APPLICATION****RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 2814****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of

Shunichi SEKI et al.

Application No.: 09/423,969

Filed: November 17, 1999

Group Art Unit: 2814

Examiner: A. Mai

Docket No.: 104741

#16/Ext.  
w/ C (NEI)  
marsha  
3/6/03For: **METHOD OF FORMING THIN FILM PATTERNING SUBSTRATE INCLUDING  
FORMATION OF BANKS (AS AMENDED)****AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116** **FAX RECEIVED**Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

FEB 03 2003

TECHNOLOGY CENTER 2800

Sir:

In reply to the Office Action mailed September 13, 2003, the period for reply being extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

**IN THE TITLE:**

Please replace the title so that it reads as follows:

**METHOD OF FORMING THIN FILM PATTERNING SUBSTRATE INCLUDING  
FORMATION OF BANKS**

**IN THE SPECIFICATION:**

Page 46, line 24 through Page 47, line 5, delete current paragraph and insert therefore:

Next, the second interlayer insulating film 52 is formed and a contact hole is formed in this interlayer insulating film in the portion corresponding to the relay electrode 35. Next,

Please  
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AM 2/13/03